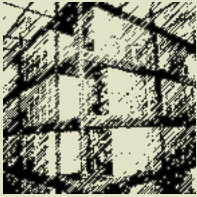


JPL



*Presentation to 2004 Workshop on Extreme
Supercomputing Panel:*

Roadmap and Change

How Much and How Fast

Thomas Sterling

California Institute of Technology

and

NASA Jet Propulsion Laboratory

October 12, 2004



2⁹ Years Ago Today



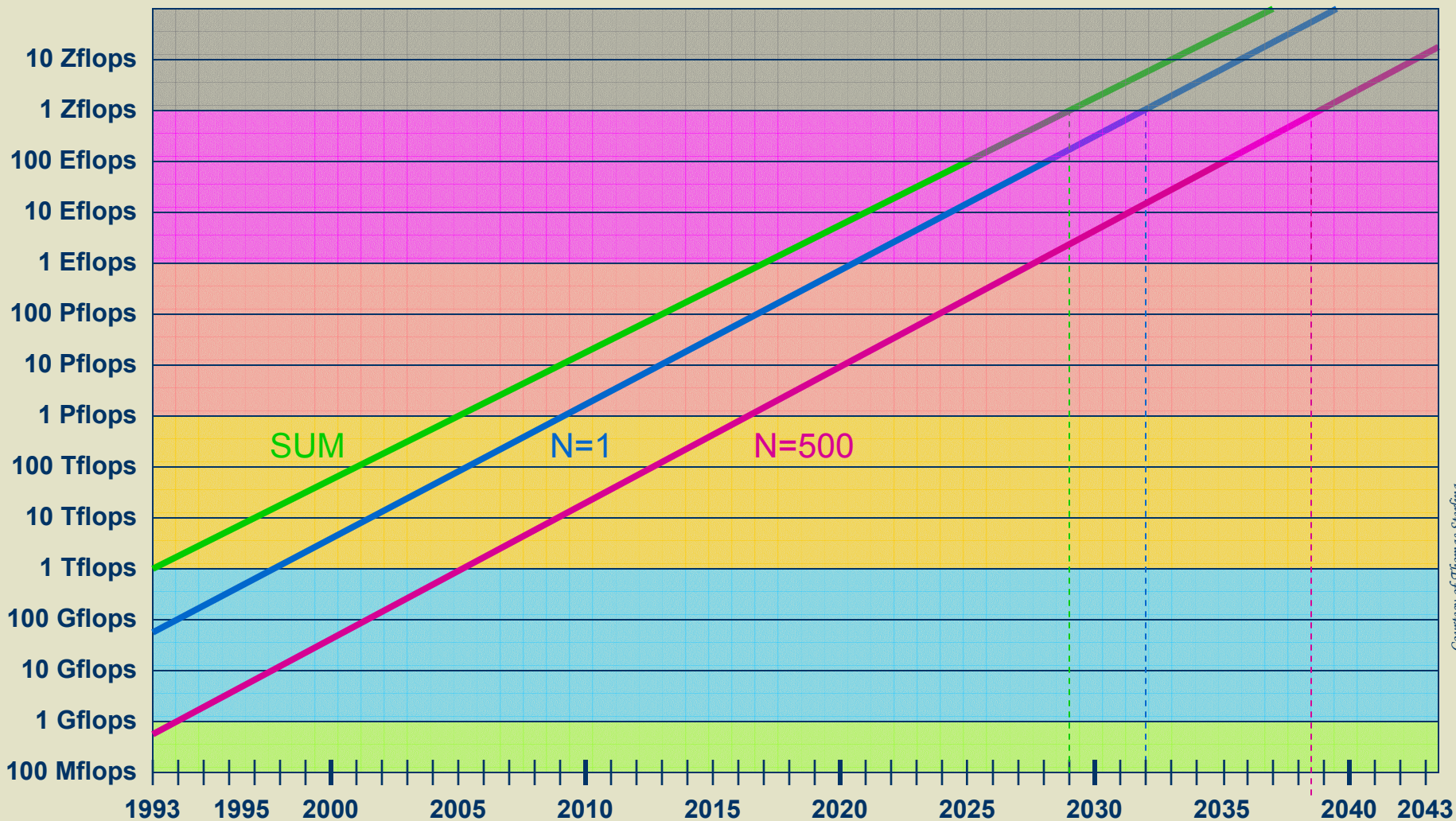
October 12, 2004

Thomas Sterling - Caltech & JPL

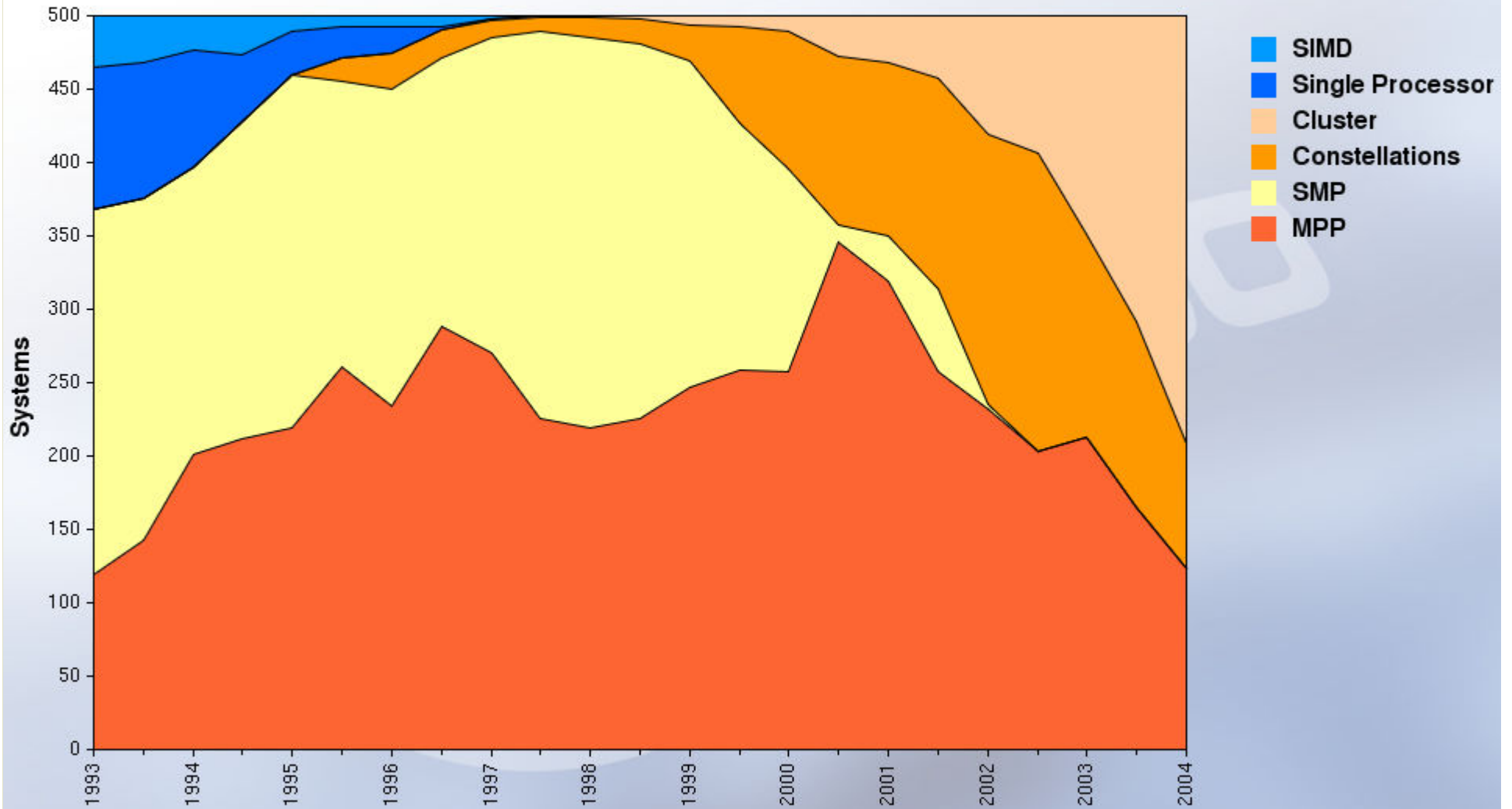
2

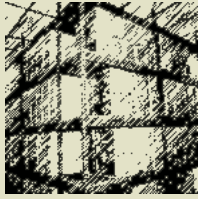


Linpack Zettaflops in 2032



Courtesy of Thomas Sterling

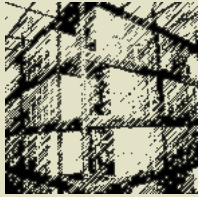




The Way We Were: 1974

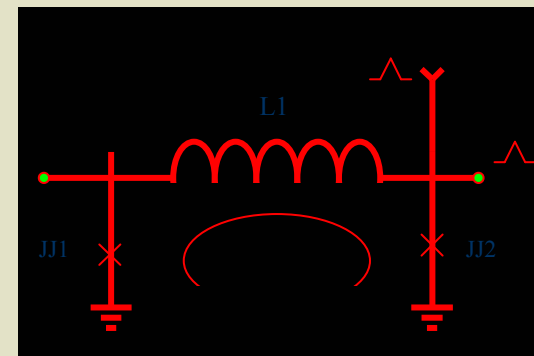
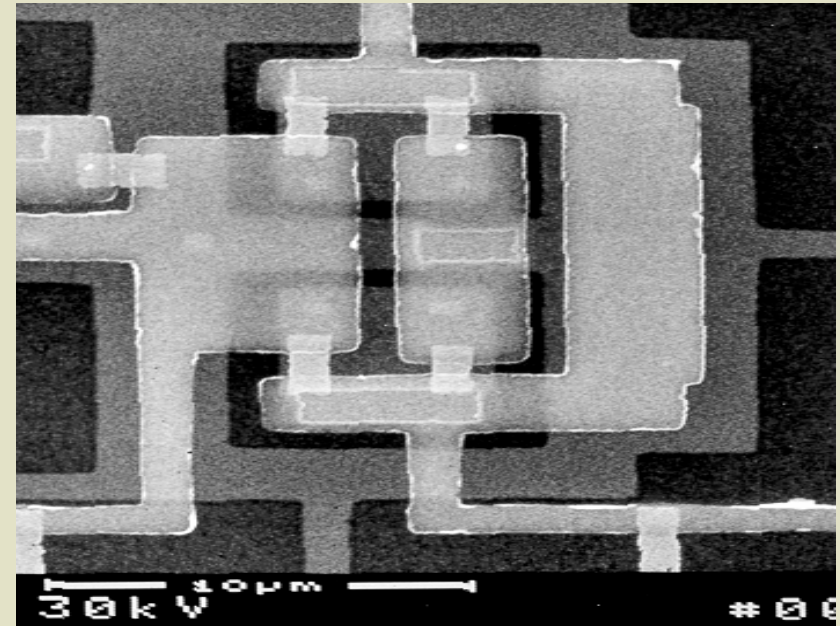
- ◆ IBM 370 market mainstream
 - Approx. 1 Mflops
- ◆ DEC PDP-11 geeks delight
- ◆ Seymour Cray started working on Cray-1
 - Approx. 100 Mflops
- ◆ 2nd generation microprocessor
 - e.g. Intel 8008
- ◆ Core memory
- ◆ 1103 1Kx1 DRAM chips
- ◆ Punch cards, paper tapes, teletypes, selectrics

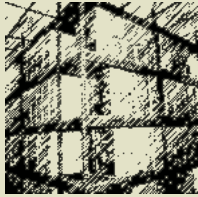




What Will Be Different

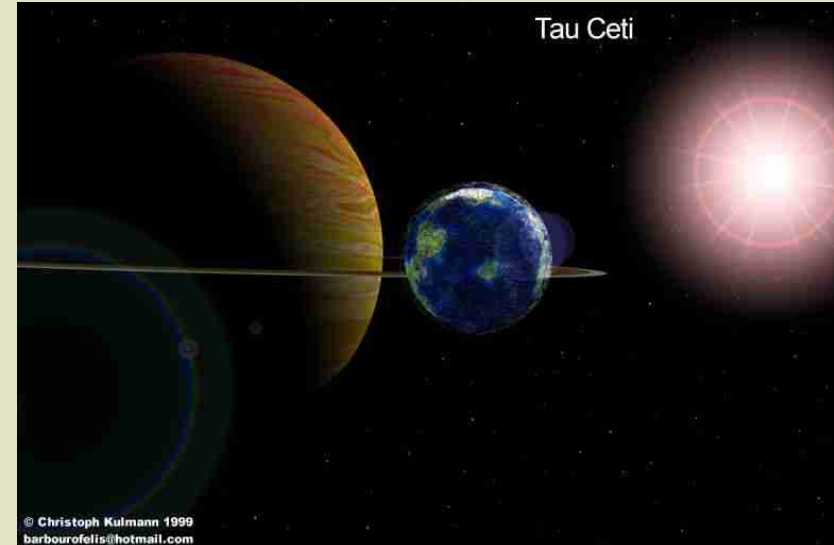
- ◆ Moore's Law will have flatlined
- ◆ Nano-scale atomic level devices
 - Assuming we solve lithography problem
- ◆ Local clock rates ~ 100 GHz
 - Fastest today is > 700 GHz
- ◆ Local actions strongly preferential to global actions
- ◆ Non-conventional technologies may be employed
 - Optical
 - Quantum dots
 - Rapid Single Flux Quantum (RSFQ) gates





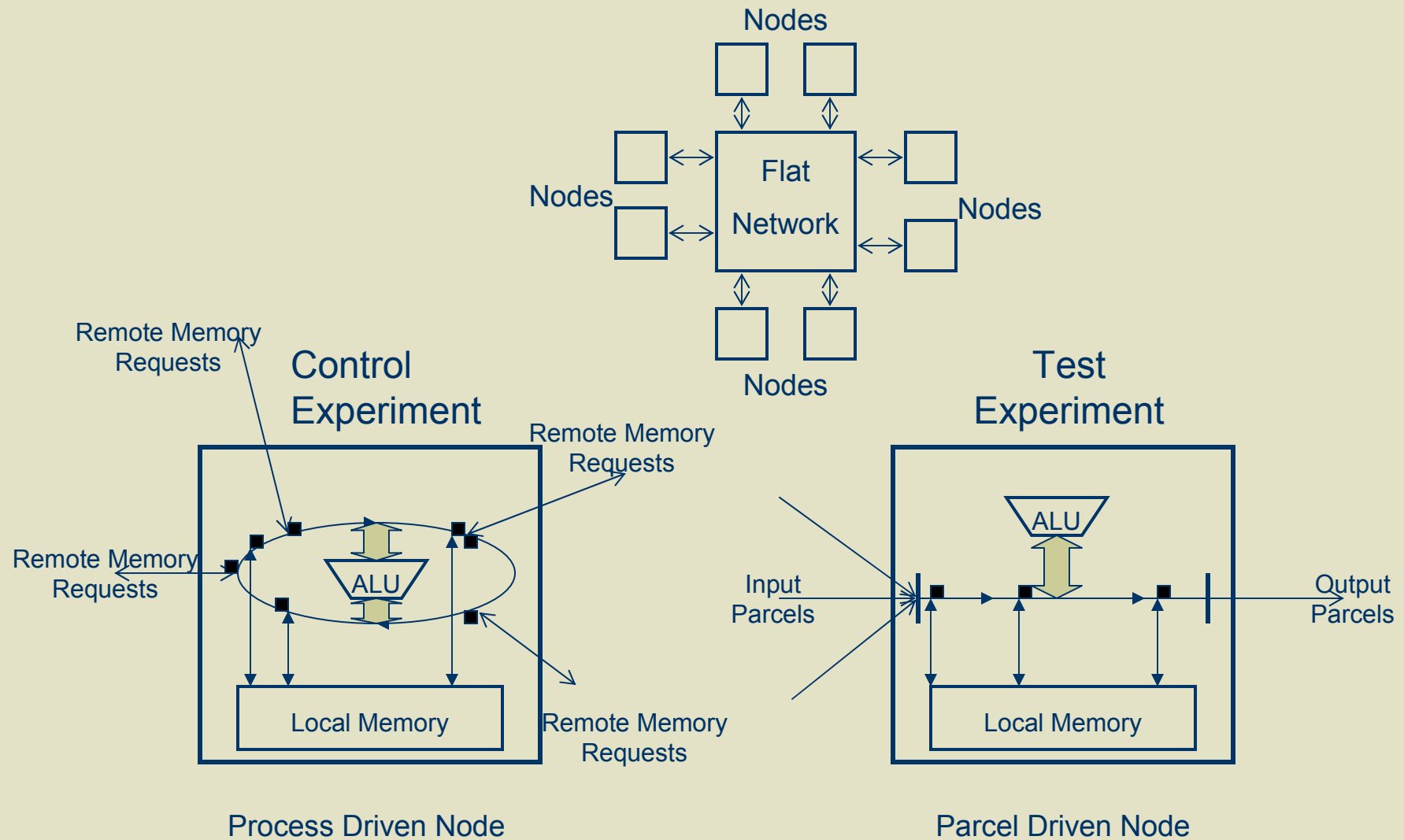
What we will need

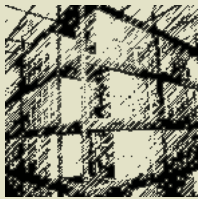
- ◆ 1 nano-watt per Megaflops
 - Energy received from Tau Ceti (per m²)
- ◆ Approximately 1 square meter for 1 Zetaflops ALUs
 - 10 billion execution sites
- ◆ > 10 billion-way parallelism
- ◆ Including memory and communications: 2000 m²
- ◆ 3-D packaging (4m)³
- ◆ Global latency of ~ 10,000 cycles
- ◆ Including average latency, => 1 trillion-way parallelism





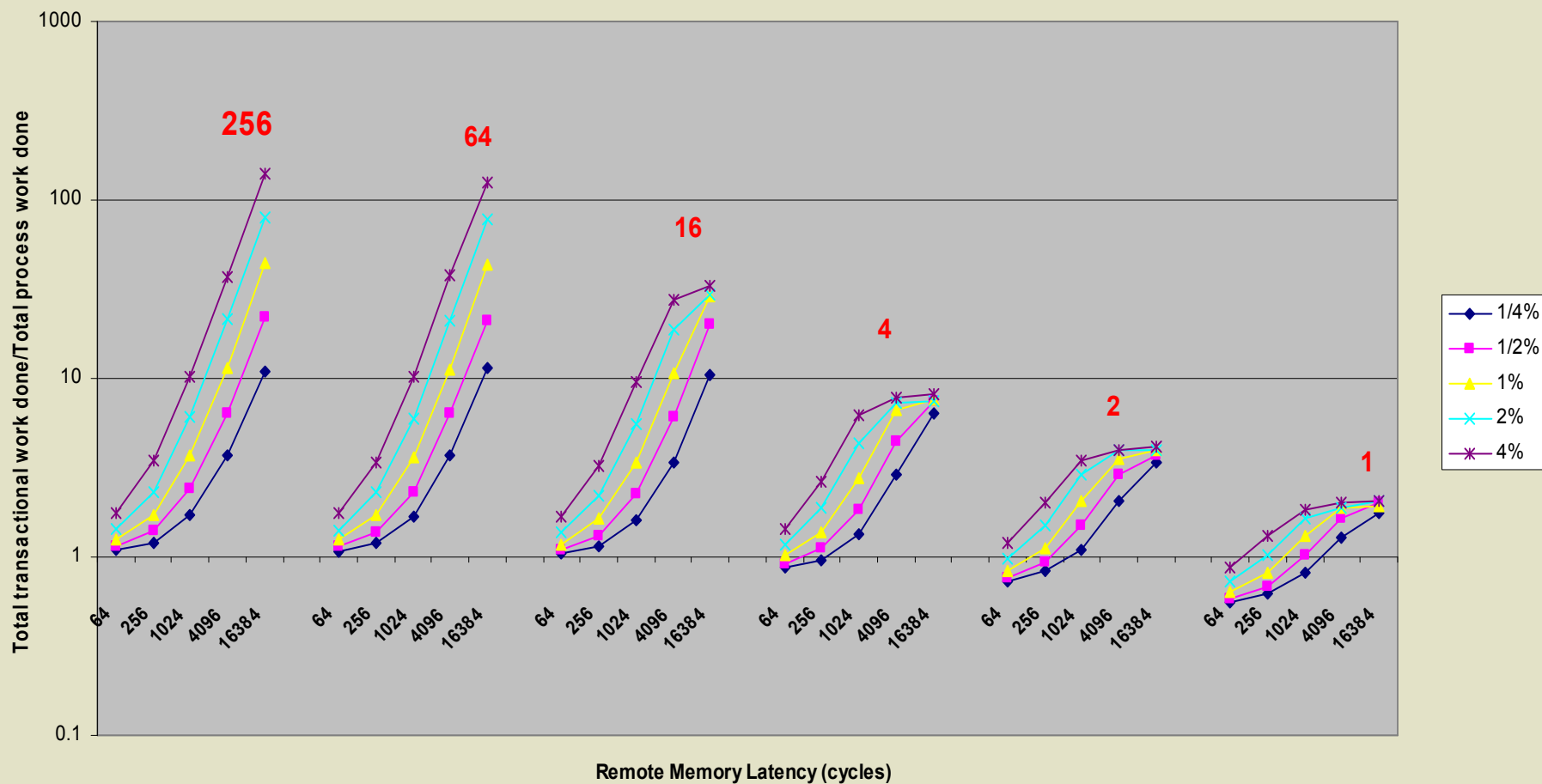
Parcel Simulation Latency Hiding Experiment

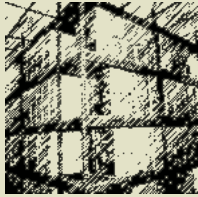




Latency Hiding with Parcels with respect to System Diameter in cycles

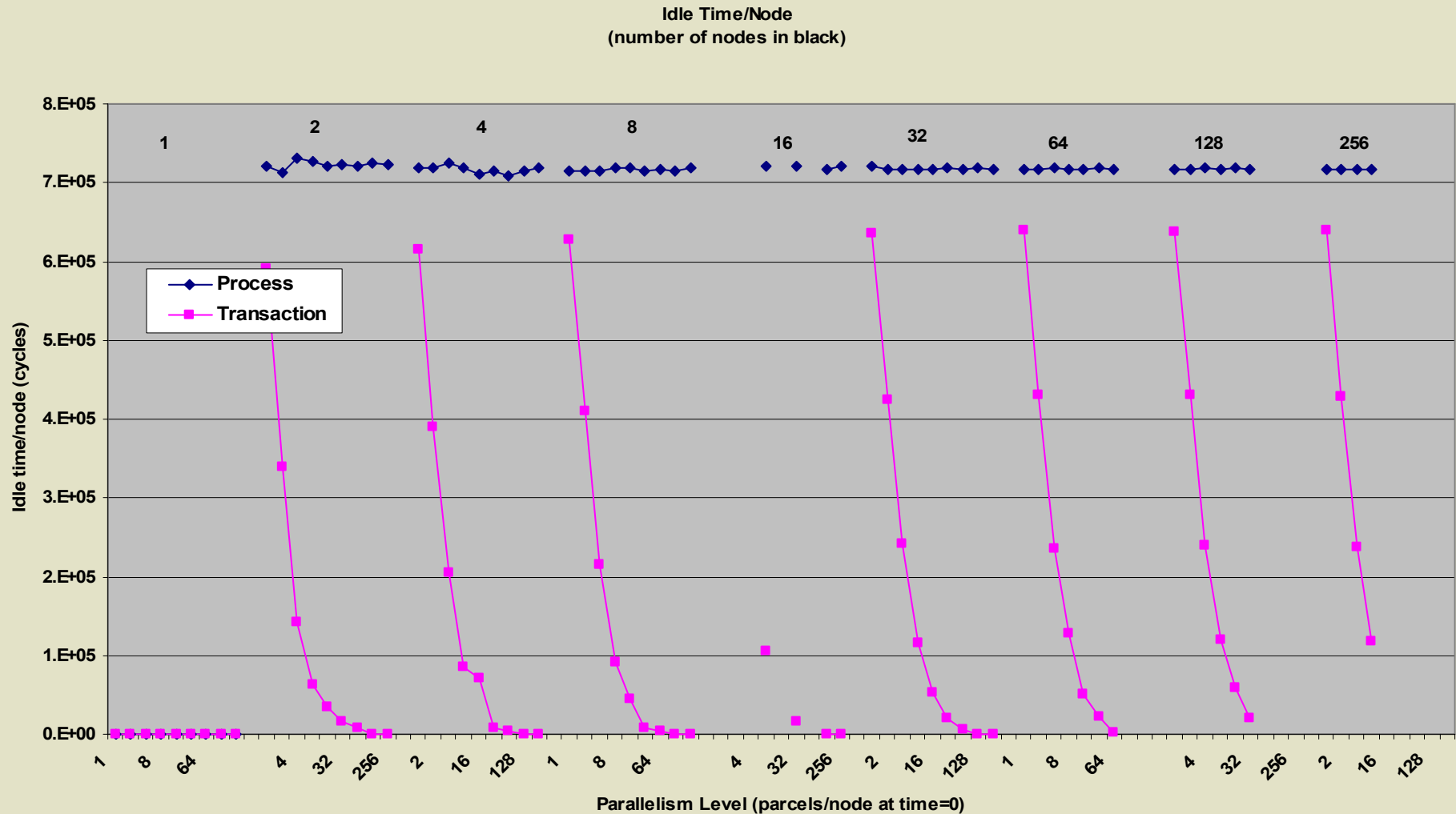
Sensitivity to Remote Latency and Remote Access Fraction
16 Nodes
deg_parallelism in RED (pending parcels @ t=0 per node)





Latency Hiding with Parcels

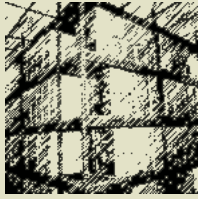
Idle Time with respect to Degree of Parallelism





Architecture Innovation

- ◆ Extreme memory bandwidth
- ◆ Active latency hiding
- ◆ Extreme parallelism
- ◆ Message-driven split-transaction computations (parcels)
- ◆ PIM
 - e.g. Kogge, Draper, Sterling, ...
 - Very high memory bandwidth
 - Lower memory latency (on chip)
 - Higher execution parallelism (banks and row-wide)
- ◆ Streaming
 - Dally, Keckler, ...
 - Very high functional parallelism
 - Low latency (between functional units)
 - Higher execution parallelism (high ALU density)



Continuum Computer Architecture

- ◆ Merges state, logic, and communication in single building block
- ◆ Parcel driven computation
 - Fine grain split transaction computing
 - Move data through vectors of instructions in store
 - Move instruction stream through vector of data
 - Gather-scatter an intrinsic
 - Very efficient *Futures* for produces-multi-consumer computing
- ◆ Combines strengths of PIM and Streaming
 - All register architecture (fully associative)
 - Functional units within a cycle of neighbors
 - Extreme parallelism
 - Intrinsic latency hiding

COMMUNICATIONS

March 2001—Volume 44, Number 3

of the ACM

Phillip Armour Norman Badler Gordon Bell Steven Bellovin

James Bennett Hal Berghel Grady Booch Anita Borg Michael Bove

Eric Brewer Dan Bricklin Kilnam Chon Ellen Christiansen

Jacques Cohen Rita Colwell Larry Constantine Martin Cooper

Robert Cringely Jon Crowcroft **THE** Peter Denning Whitfield Diffie

Edsger Dijkstra Susan Dray Usama Fayyad Christopher Fry

Ravi Ganesan John Glenn **NEXT** Mark Gorenberg Jim Gray

Andrew Grosso Karen Holtzblatt Thomas Horan Joseph Jacobson

Ramesh Jain Christopher Johnson **1,000** Leon Kappelman

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Brock Meeks Cameron Miner **YEARS** Michael Muller

Bonnie Nardi Donald Norman Peter Neumann Cheri Pancake

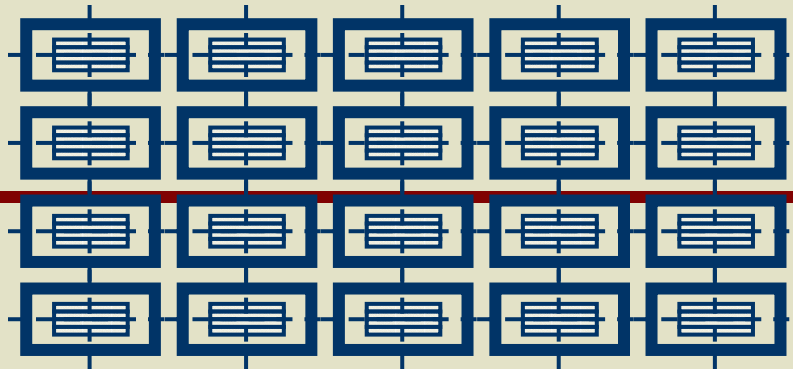
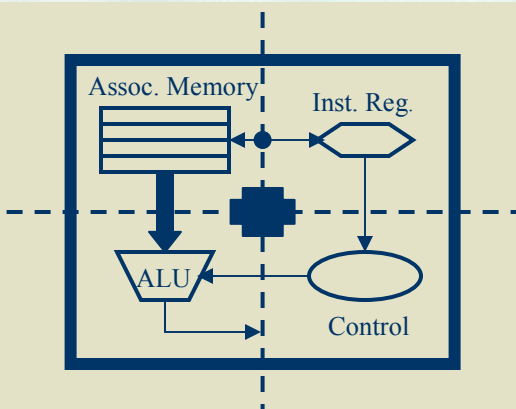
David Parnas Jean-François Pódevin Mitchel Resnick Doug Riecken

Pamela Samuelson Roger Schank Bruce Schneier Ari Schwartz

Steven Schwartz Ted Selker Richard Stallman Thomas Sterling

Anthony Townsend Dennis Tschritzis Andres van Dam

Hal Varian Ron Vetter Jim Waldo Ann Winblad



Continuum Computer Architecture for Exaflops Computation

THOMAS STERLING

THE ultimate computers in our long-term future will deliver exaflops-scale performance (or greater) and will look very different from today's microprocessors and massively parallel computers. Ironically, however, their alien structures and operational behavior can be inferred from the same technology trends driving development of today's conventional computing systems.

A vision of future computer architectures that are direct extrapolations of current trends is easily inspired by the explosive growth of today's computer performance, price-performance, and applications (driven by Moore's Law for device technology), as well as the more dramatic paradigm shifts brought on by the Internet, the Web, and grids. Yet an examination of these trends also reveals the possibility of something quite different in how we'll organize, design, and fabricate our largest computers in the future. They even set the stage for a revolution in computer architecture that may displace the venerable and highly successful "von Neumann model" and its pre-eminence over the past 50 years.

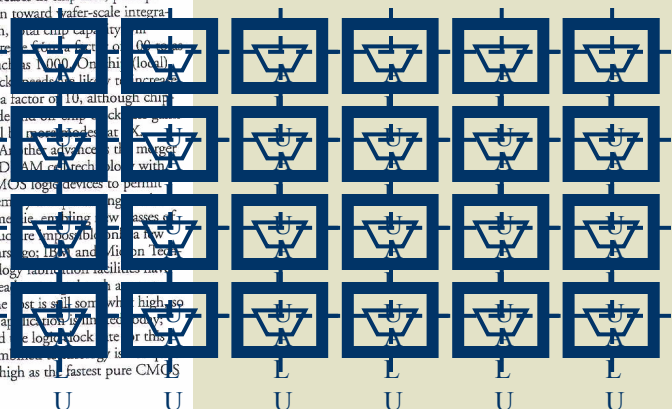
One class of innovative computing system being explored today by computer scientists at the California Institute of Technology's Center for Advanced

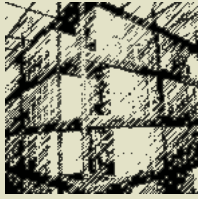
Computing Research is the continuum computer architecture (CCA), an ultra-fine-grain uniform structure that approximates a continuous 3D execution medium enabled through next-generation submicron logic devices. Future computers—whether major exaflops engines used to design and simulate everything from controlled fusion reactors to rapid-response medicines, to compact low-power robot brains for autonomous control of spacecraft, airplanes, automobiles, and homes, to embedded smartware in our clothes and bodies—may look less like today's microprocessors and much more like CCAs.

Several concurrent trends in semiconductor and other technologies will force a rethinking of the physical structure and logical operation of parallel computer systems. Lithographic feature size will be driven below 0.05 microns

by 2010, increasing the number of devices per unit area by at least an order of magnitude by today's standards. Combined with increases in chip area, perhaps even toward wafer-scale integration, that chip capacity will increase by a factor of 100 or more. On the other hand, clock speeds are likely to increase by a factor of 10, although chip-wide bus or network protocols will limit the speed at which data can be moved.

As the advantages of CMOS logic devices to permit massive scaling of device counts are realized, the same scaling will be applied to the structure of IPAs and other technologies that facilitate massive scaling of device counts. The result is still some way off, but its application to the design of a computer architecture that is as high as the fastest pure CMOS





Conclusions

- ◆ Zettaflops at nano-scale technology is possible
 - Size requirements tolerable
 - But packaging is a challenge;
 - Latency challenge does not sink the idea
- ◆ Major obstacles
 - Power
 - Latency
 - Parallelism
 - Reliability
 - Programming
- ◆ Architecture can address many of these
- ◆ Continuum Computing Architecture
 - Combines advantages of PIM and streaming
 - Strong candidate for future Zettaflops computer

